APPLICA	BLE STAN	DARD									
	OPERATING TEMPERATURE RANGE					RAGE IPERATURE RANGE		-10	-10°C TO +60°C(NC		3)
RATING	OPERATING HUMIDITY RANGE		20 % 10 00 % (NOTE 2)			RAGE MIDITY RANGE		4	40 % TO 70 %(NO		3)
	VOLTAGE		AC 150 V			ICABLE NECTOF			DF13-*S-1.25C		
	CURRENT		1 A	. , ,		LICABLE ITACT			DF13(G)-2630SCF, DF13-3032SCF		
			SPECI	FICA	OIT	NS		•			
IT	EM		TEST METHOD				REQUIREMENTS				AT
CONSTR	UCTION										
GENERAL EX	AMINATION	VISUALLY AND BY MEASURING INSTRUMENT.				ACCORDING TO DRAWING.				X	Х
MARKING		CONFIRMED VISUALLY.								X	Х
ELECTR	IC CHARA	CTERISTICS									
CONTACT RESISTANCE		100 m A (DC OR 1000 Hz).				30 mΩ MAX.				Х	_
INSULATION		100 V DC.				500 MΩ MIN.				Х	_
RESISTANCE VOLTAGE PROOF		500 V AC FOR 1 min.				NO FLASHOVER OR BREAKDOWN.				X	+_
		RACTERISTICS									
MECHANICA		30 TIMES INSERTIONS AND EXTRACTIONS.				① CONTACT RESISTANCE: 30 mΩ MAX.					Τ_
OPERATION		TIMES INSERTIONS AND EXTRACTIONS.				② NO DAMAGE, CRACK OR LOOSENESS OF PARTS.				- X	
VIBRATION		0.75 mm, AT 2 h, FOR 3 DIRECTIONS.				 NO ELECTRICAL DISCONTINUITY OF 1μs. NO DAMAGE, CRACK OR LOOSENESS OF PARTS. 					_
SHOCK		490 m/s ² DURATION OF PULSE 11 ms AT 3 TIMES FOR 3 DIRECTIONS.								Х	_
ENVIRO	MENTAL	CHAR	ACTERISTICS		ı						1
RAPID CHAI		TEMPERATURE -55 \rightarrow 5 TO 35 \rightarrow +85 \rightarrow 5 TO 35 °C (1) CONTACT RESISTANCE: 30m Ω MAX.									
TEMPERATURE		TIME $30 \rightarrow 10 \text{ TO } 5 \rightarrow 30 \rightarrow 10 \text{ TO15 min}$ UNDER 5 CYCLES.									_
DAMP HEAT		EXPOSED AT 40 ± 2 °C, 90 TO 95 %, 96 h.			③ NO DAMAGE, CRACK OR LOOSENESS OF PARTS.						
(STEADY STATE)		EXT OSED XT 40 12 0, 90 10 93 70, 90 II.				Si Tructo.					_
RESISTANCE TO		1) REFLOW SOLDERING				NO DEFORMATION OF CASE OF EXCESSIVE LOOSENESS OF THE TERMINALS.					
SOLDERING HEAT		≪REFLOW AREA≫ MAX250°C WITHIN 10 sec MIN 230°C WITHIN 60 sec								X	_
		≪PREHEATING AREA≫ 170°C to 190°C 60 sec to 120 sec PUT THROUGH IN REFLOW FURNACE TWICE LEAVE IN AMBIENT TEMPERATURE AND HUMIDITY FOR 1 HOUR. CONNECTOR TEMPERATURE TO BE AMBIENT FOR SECOND REFLOW. 2) MANUAL SOLDERING SOLDERING IRON TEMPERATURE :350°C,									
		SOLDERING TIME : 3sec. NO STRENGTH ON CONTACT.									
SOLDERABILITY		SOLDERED AT SOLDER TEMPERATURE,				SOLDER SHALL COVER A MINIMUM OF					
		245±3°C	245±3°C FOR INSERTION DURATION, 3sec.				95 % OF THE SURFACE BEING IMMERSED.				_
REMARKS	IDE THE TEMP		DICINIC BY CURRENT								
NOTE1: INCLU		EKATUKE	RISING BY CURRENT								
			LONG TERM STORAGE FOR U								
	R MOUNTED (ISPORTATION.	ON PCB B	OARD, OPERATING TEMPERA	ATURE AN	ND HUM	IDITY R.	ANGE IS A	PPLIED	FOR INTERIM STOR	AGE D	URING
COUN					DESIG	GNED CHECKED					ATE
\triangle											
Unless otherwise specified, ref			, refer to IEC 60512.			APPROVED		ΕD	HS.OKAWA	18.0	04.05
							CHECKE	D	TS.FUKUSHIMA	18.0	04.05
							DESIGNE	D	TS.KUMAZAWA	18.0	04.05
						DRAWN		1	MK.INOUE	UE 18.04	
Note QT:Qualification Test AT:Assurance Test X:Applicable Test D					DF	RAWIN	G NO.		ELC-083664-75-00		
HS.	SPECIFICATION SHEET				PART	NO.		DF1	DF13-*P-1.25V(75)		
	HIR	HIROSE ELECTRIC CO., LTD.			CODE	NO.	O.		CL536		1/1